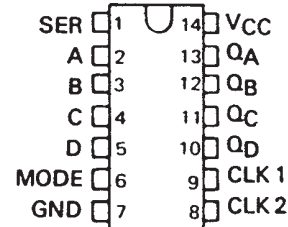


SN5495A, SN54LS95B SN7495A, SN74LS95B 4-BIT PARALLEL-ACCESS SHIFT REGISTERS

SDLS128 - MARCH 1974 - REVISED MARCH 1988

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'95A	36 MHz	195 mW
'LS95B	36 MHz	65 mW

SN5495A, SN54LS95B . . . J OR W PACKAGE
SN7495A . . . N PACKAGE
SN74LS95B . . . D OR N PACKAGE
(TOP VIEW)



description

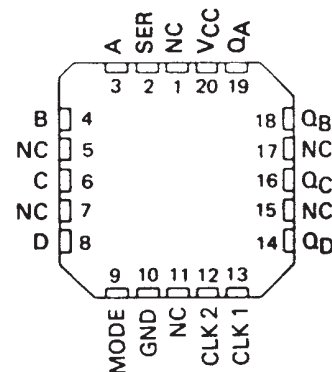
These 4-bit registers feature parallel and serial inputs, parallel outputs, mode control, and two clock inputs. The registers have three modes of operation:

- Parallel (broadside) load
- Shift right (the direction Q_A toward Q_D)
- Shift left (the direction Q_D toward Q_A)

Parallel loading is accomplished by applying the four bits of data and taking the mode control input high. The data is loaded into the associated flip-flops and appears at the outputs after the high-to-low transition of the clock-2 input. During loading, the entry of serial data is inhibited.

Shift right is accomplished on the high-to-low transition of clock 1 when the mode control is low; shift left is accomplished on the high-to-low transition of clock 2 when the mode control is high by connecting the output of each flip-flop to the parallel input of the previous flip-flop (Q_D to input C, etc.) and serial data is entered at input D. The clock input may be applied commonly to clock 1 and clock 2 if both modes can be clocked from the same source. Changes at the mode control input should normally be made while both clock inputs are low; however, conditions described in the last three lines of the function table will also ensure that register contents are protected.

SN54LS95B . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

FUNCTION TABLE

		INPUTS						OUTPUTS			
MODE CONTROL	CLOCKS		SERIAL	PARALLEL				Q_A	Q_B	Q_C	Q_D
	2 (L)	1 (R)		A	B	C	D				
H	H	X	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
H	↓	X	X	a	b	c	d	a	b	c	d
H	↓	X	X	Q_B^\dagger	Q_C^\dagger	Q_D^\dagger	d	Q_{Bn}	Q_{Cn}	Q_{Dn}	d
L	L	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
L	X	↓	H	X	X	X	X	H	Q_{An}	Q_{Bn}	Q_{Cn}
L	X	↓	L	X	X	X	X	L	Q_{An}	Q_{Bn}	Q_{Cn}
↑	L	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↓	L	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↓	L	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↑	H	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↑	H	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}

† Shifting left requires external connection of Q_B to A, Q_C to B, and Q_D to C. Serial data is entered at input D.

H = high level (steady state), L = low level (steady state), X = irrelevant (any input, including transitions)

↓ = transition from high to low level, ↑ = transition from low to high level

a, b, c, d = the level of steady-state input at inputs A, B, C, or D, respectively.

Q_{A0} , Q_{B0} , Q_{C0} , Q_{D0} = the level of Q_A , Q_B , Q_C , or Q_D , respectively, before the indicated steady-state input conditions were established.

Q_{An} , Q_{Bn} , Q_{Cn} , Q_{Dn} = the level of Q_A , Q_B , Q_C , or Q_D , respectively, before the most-recent ↓ transition of the clock.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

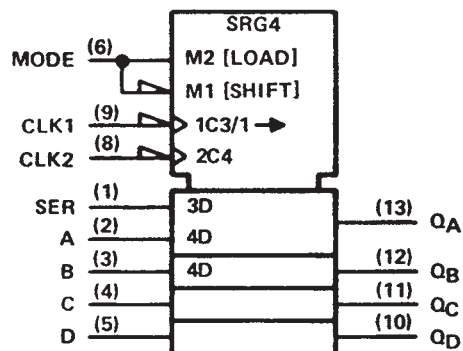
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SN5495A, SN54LS95B SN7495A, SN74LS95B 4-BIT PARALLEL-ACCESS SHIFT REGISTERS

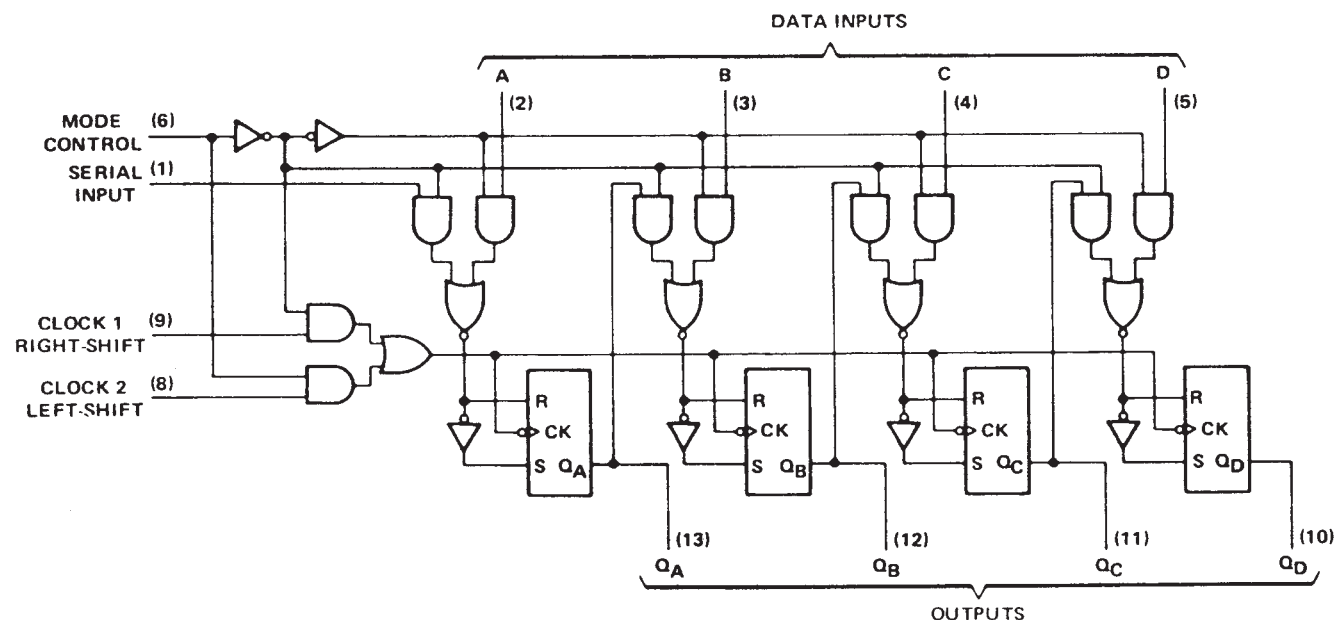
SDLS128 – MARCH 1974 – REVISED MARCH 1988

logic symbol†



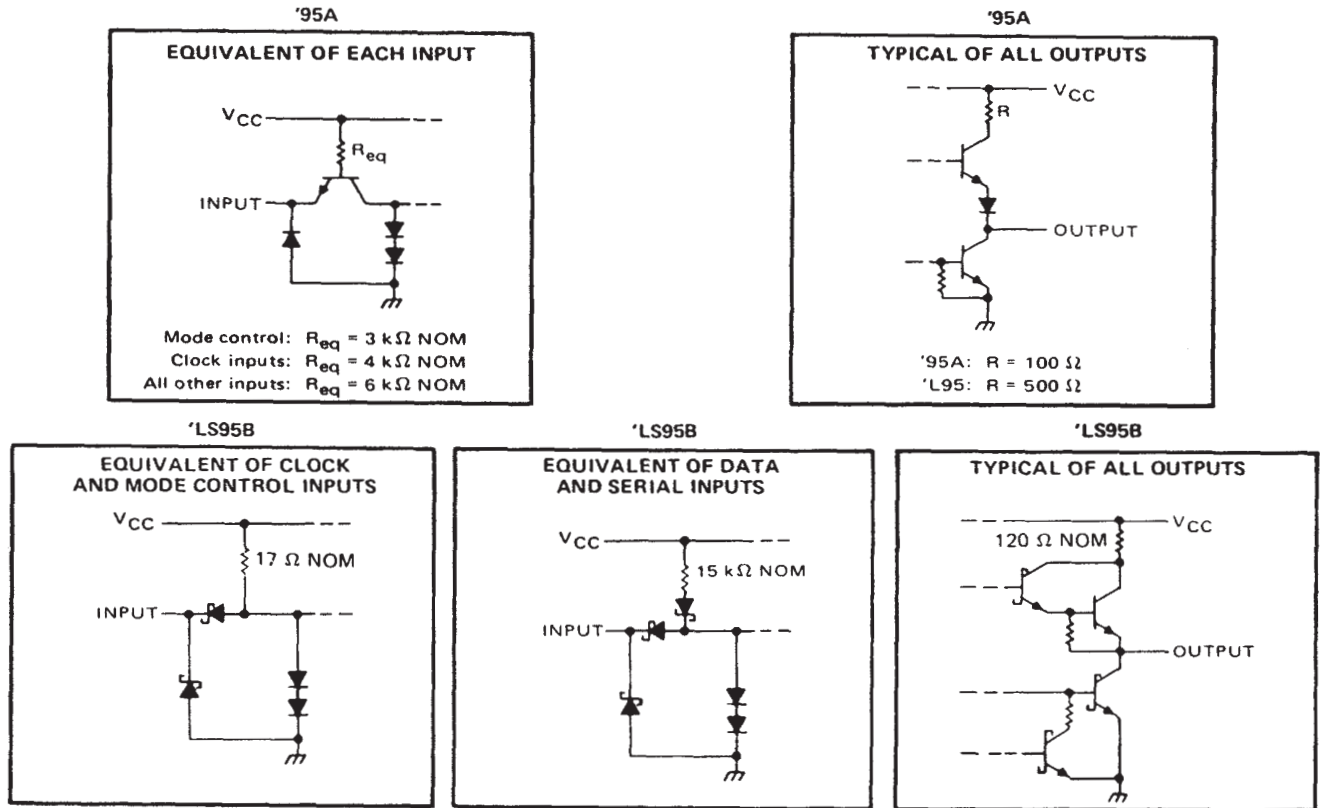
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)



SN5495A, SN54LS95B
SN7495A, SN74LS95B
4-BIT PARALLEL-ACCESS SHIFT REGISTERS
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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54'	SN54LS'	SN74'	SN74LS'	UNIT
Supply voltage, V_{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Interemitter voltage (see Note 2)	5.5		5.5		V
Operating free-air temperature range	-55 to 125		0 to 70		°C
Storage temperature range	-65 to 150		-65 to 150		°C

- NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
2. This is the voltage between two emitters of a multiple-emitter input transistor. This rating applies between the clock-2 input and the mode control input of the '95A.

**SN5495A, SN54LS95B
SN7495A, SN74LS95B
4-BIT PARALLEL-ACCESS SHIFT REGISTERS**

SDLS128 – MARCH 1974 – REVISED MARCH 1988

recommended operating conditions

	SN5495A			SN7495A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			–800			–800	μ A
Low-level output current, I_{OL}			16			16	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock pulse, $t_{w(clock)}$ (See Figure 1)	20			20			ns
Setup time, high-level or low-level data, t_{SU} (See Figure 1)	15			15			ns
Hold time, high-level or low-level data, t_H (See Figure 1)	0			0			ns
Time to enable clock 1, $t_{enable\ 1}$ (See Figure 2)	15			15			ns
Time to enable clock 2 (See Figure 2)	15			15			ns
Time to inhibit clock 1, $t_{inhibit\ 1}$ (See Figure 2)	5			5			ns
Time to inhibit clock 2, $t_{inhibit\ 2}$ (See Figure 2)	5			5			ns
Operating free-air temperature, T_A	–55		125	0		70	$^{\circ}$ C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN5495A			SN7495A			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -12\text{ mA}$			–1.5			–1.5	V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2\text{ V},$ $V_{IL} = 0.8\text{ V}, I_{OH} = -800\text{ }\mu\text{A}$	2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2\text{ V},$ $V_{IL} = 0.8\text{ V}, I_{OL} = 16\text{ mA}$		0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5\text{ V}$			1			1	mA
I_{IH}	High-level input current	Serial, A, B, C, D, Clock 1 or 2			40			40	μ A
		Mode control			80			80	
I_{IL}	Low-level input current	Serial, A, B, C, D, Clock 1 or 2			–1.6			–1.6	mA
		Mode control			–3.2			–3.2	
I_{OS}	Short-circuit output current§	$V_{CC} = \text{MAX}$	–18		–57	–18		–57	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$, See Note 3		39	63		39	63	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5\text{ V}, T_A = 25^{\circ}\text{C}$.

§ Not more than one output should be shorted at a time.

NOTE 3: I_{CC} is measured with all outputs and serial input open; A, B, C, and D inputs grounded; mode control at 4.5 V; and a momentary 3 V, then ground, applied to both clock inputs.

switching characteristics, $V_{CC} = 5\text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max} Maximum clock frequency	$C_L = 15\text{ pF}, R_L = 400\text{ }\Omega,$ See Figure 1	25	36		MHz
t_{PLH} Propagation delay time, low-to-high-level output from clock			18	27	ns
t_{PHL} Propagation delay time, high-to-low-level output from clock			21	32	ns



SN5495A, SN54LS95B
SN7495A, SN74LS95B
4-BIT PARALLEL-ACCESS SHIFT REGISTERS
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recommended operating conditions

	SN54LS95B			SN74LS95B			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			–400			–400	μ A
Low-level output current, I_{OL}			4			8	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock pulse, $t_{w(clock)}$ (see Figure 1)	20			20			ns
Setup time, high-level or low-level data, t_{su} (see Figure 1)	20			20			ns
Hold time, high-level or low-level data, t_h (see Figure 1)	20			10			ns
Time to enable clock 1, $t_{enable\ 1}$ (see Figure 2)	20			20			ns
Time to enable clock 2, $t_{enable\ 2}$ (see Figure 2)	20			20			ns
Time to inhibit clock 1, $t_{inhibit\ 1}$ (see Figure 2)	20			20			ns
Time to inhibit clock 2, $t_{inhibit\ 2}$ (see Figure 2)	20			20			ns
Operating free-air temperature, T_A	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS95B			SN74LS95B			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH} High-level input voltage		2			2			V
V_{IL} Low-level input voltage				0.7			0.8	V
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			–1.5			–1.5	V
V_{OH} High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, I_{OH} = -400 \mu\text{A}$	2.5	3.4		2.7	3.4		V
V_{OL} Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
	$I_{OL} = 8 \text{ mA}$					0.35	0.5	
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH} High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			20			20	μ A
I_{IL} Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			–0.4			–0.4	mA
I_{OS} Short-circuit output current§	$V_{CC} = \text{MAX}$	–20		–100	–20		–100	mA
I_{CC} Supply current	$V_{CC} = \text{MAX},$ See Note 3		13	21		13	21	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 3: I_{CC} is measured with all outputs and serial input open; A, B, C, and D inputs grounded; mode control at 4.5 V; and a momentary 3 V, then ground, applied to both clock inputs.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

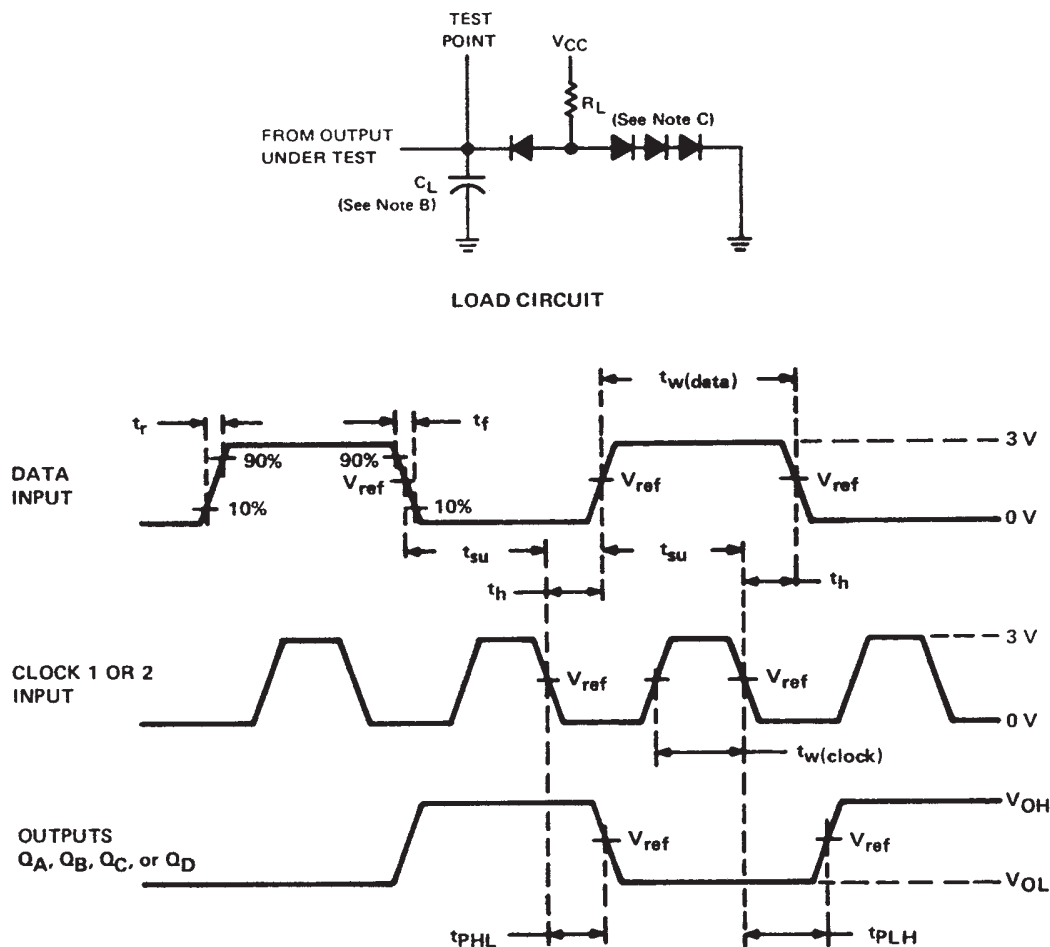
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max} Maximum clock frequency	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$ See Figure 1	25	36		MHz
t_{PLH} Propagation delay time, low-to-high-level output from clock			18	27	ns
t_{PHL} Propagation delay time, high-to-low-level output from clock			21	32	ns



SN5495A, SN54LS95B SN7495A, SN74LS95B 4-BIT PARALLEL-ACCESS SHIFT REGISTERS

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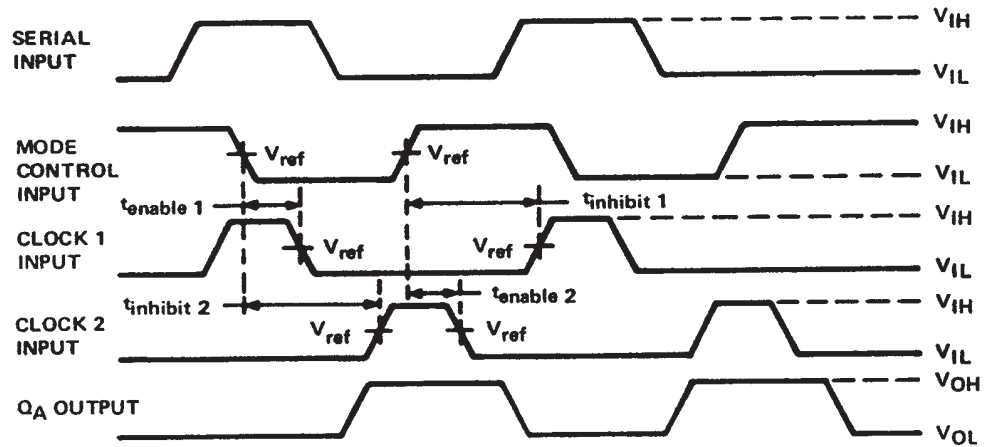
PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Input pulses are supplied by a generator having the following characteristics: $t_r \leq 10$ ns, $t_f \leq 10$ ns, and $Z_{out} \approx 50 \Omega$. For the data pulse generator, PRR = 500 kHz; for the clock pulse generator, PRR = 1 MHz. When testing f_{max} , vary PRR. For '95A, $t_w(\text{data}) \geq 20$ ns, $t_w(\text{clock}) \geq 15$ ns. For 'LS95B, $t_w(\text{data}) \geq 20$ ns, $t_w(\text{clock}) \geq 15$ ns.
- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N3064 equivalent.
- D. For '95A, $V_{ref} = 1.5$ V; for 'LS95B, $V_{ref} = 1.3$ V.

VOLTAGE WAVEFORMS
FIGURE 1-SWITCHING TIMES

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Input is at a low level.
 B. For '95A, $V_{ref} = 1.5\text{ V}$; for 'LS958, $V_{ref} = 1.3\text{ V}$.

VOLTAGE WAVEFORMS
 FIGURE 2-CLOCK ENABLE/INHIBIT TIMES

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN5495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN7495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN7495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN7495AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7495AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS95BD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5495AW	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5495AW	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

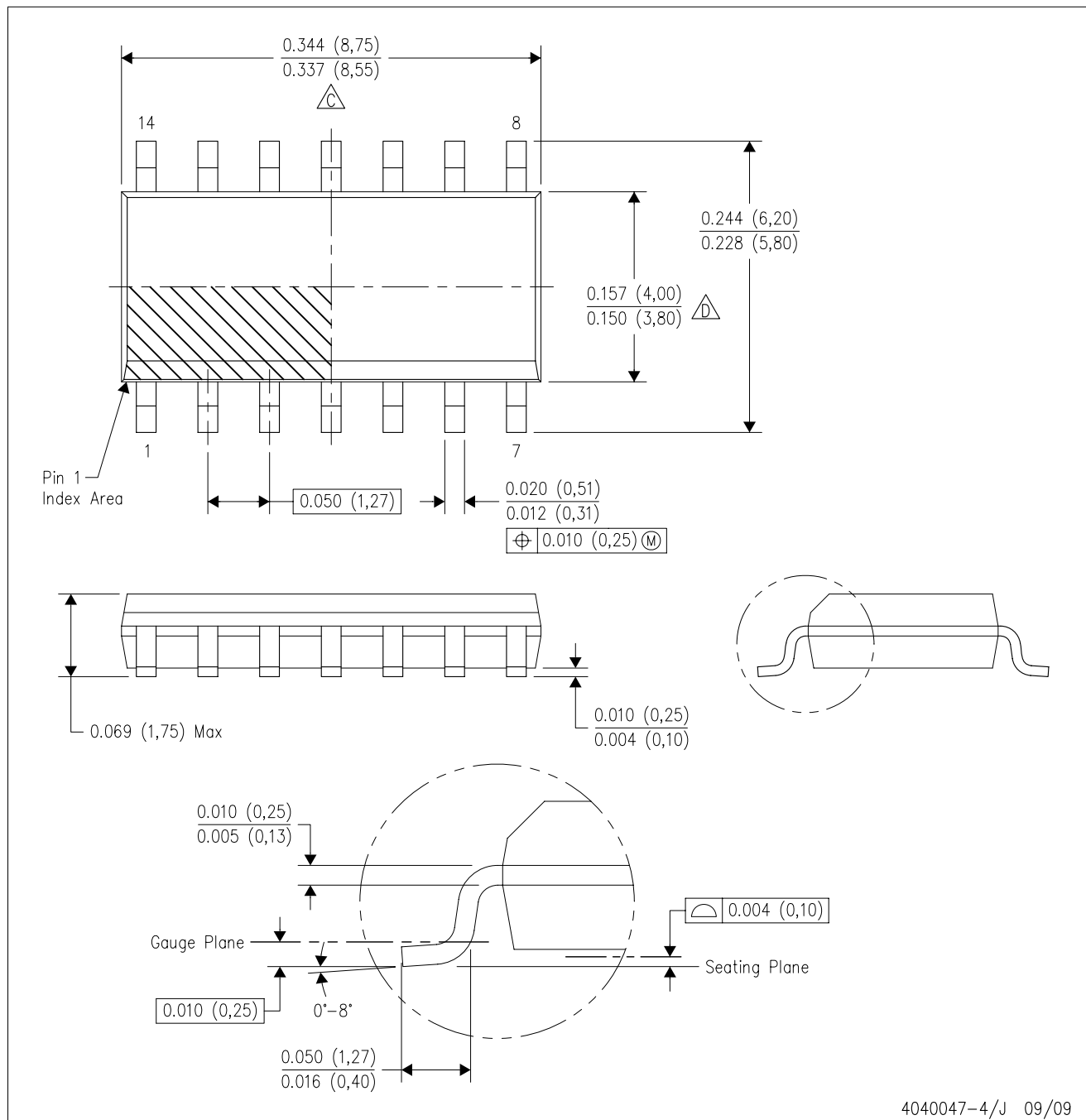


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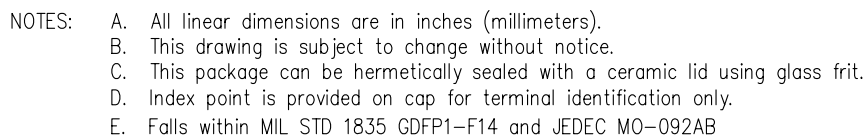
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

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SN74LS95BD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
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SNJ5495AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5495AW	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

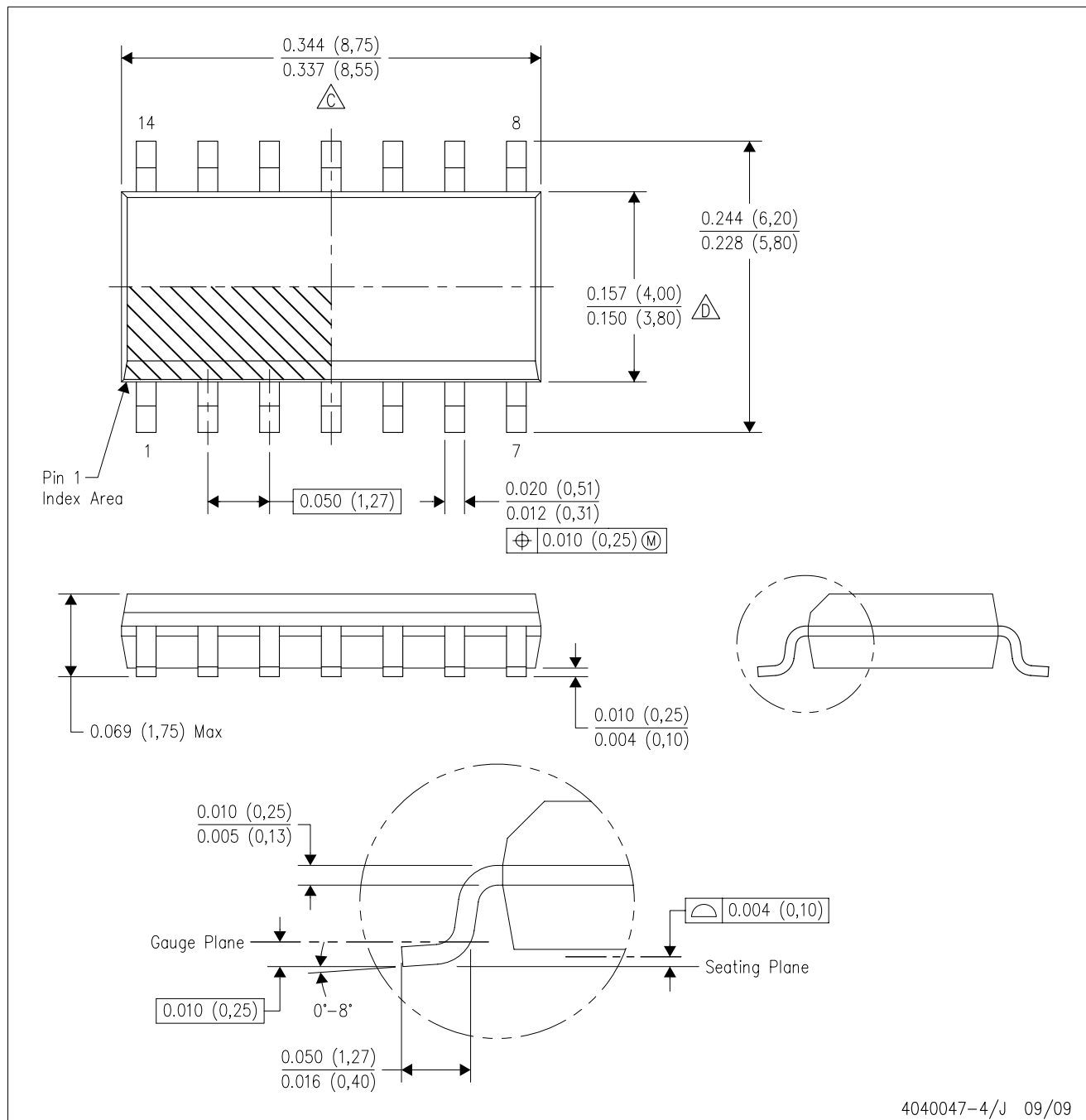


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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